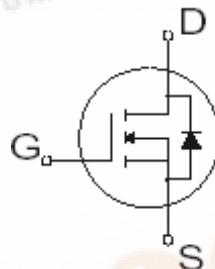




75NF75

HEXFET® Power MOSFET

- Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast switching
- Ease of Paralleling
- Simple Drive Requirements



V_{DSS} = 75V

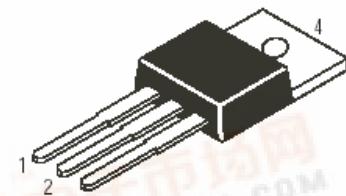
I_{D25} = 75A

R_{DSON} = 13.0 mΩ

Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50watts. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



Pin1-Gate
Pin2-Drain
Pin3-Source

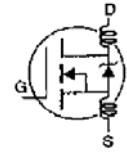
Absolute Maximum Ratings

	Parameter	Max.	Units
I _D @T _c =25°C	Continuous Drain Current, V _{GS} @10V	75 ①	A
I _D @T _c =100°C	Continuous Drain Current, V _{GS} @10V	60	
I _{DM}	Pulsed Drain Current ②	300	
P _D @T _c =25°C	Power Dissipation	200	W
	Linear Derating Factor	1.5	W/°C
V _{GS}	Gate-to-Source Voltage	±20	V
E _{AR}	Single Pulse Avalanche Energy ③	23	mJ
dv/dt	Peak Diode Recovery dv/dt ④	5.9	V/ns
T _J	Operating Junction and	-55 to +175	°C
T _{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300(1.6mm from case)	
	Mounting Torque,6-32 or M3 screw	10 lbf.in(1.1N.m)	

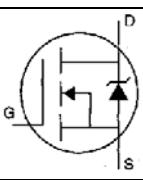
Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
R _{θJC}	Junction-to-case	—	—	0.65	°C /W
R _{θCS}	Case-to-Sink, Flat, Greased Surface	—	0.50	—	
R _{θJA}	Junction-to-Ambient	—	—	62	

Electrical Characteristics @ $T_J=25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	75	—	—	V	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.074	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D=1\text{mA}$
$R_{\text{DS}(\text{on})}$	Static Drain-to-Source On-resistance	—	—	13.0	$\text{m}\Omega$	$V_{\text{GS}}=10\text{V}, I_D=40\text{A}$ ⑤
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$
g_{fs}	Forward Transconductance	20	—	—	S	$V_{\text{DS}}=25\text{V}, I_D=40\text{A}$ ⑤
I_{DSS}	Drain-to-Source Leakage current	—	—	25	μA	$V_{\text{DS}}=75\text{V}, V_{\text{GS}}=0\text{V}$
		—	—	250		$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}, T_J=150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward leakage	—	—	100	nA	$V_{\text{GS}}=20\text{V}$
	Gate-to-Source Reverse leakage	—	—	-100		$V_{\text{GS}}=-20\text{V}$
Q_g	Total Gate Charge	—	—	160	nC	$I_D=40\text{A}$
Q_{gs}	Gate-to-Source charge	—	—	29		$V_{\text{DS}}=60\text{V}$
Q_{gd}	Gate-to-Drain ("Miller") charge	—	—	55		$V_{\text{GS}}=10\text{V}$ See Fig.6 and 13 ⑤
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	—	13	—		$V_{\text{DD}}=38\text{V}$
t_r	Rise Time	—	64	—	nS	$I_D=40\text{A}$
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time	—	49	—		$R_G=2.5\Omega$
t_f	Fall Time	—	48	—		$V_{\text{GS}}=10\text{V}$ See Figure 10 ⑤
L_D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6mm(0.25in.) from package and center of die contact
L_s	Internal Source Inductance	—	7.5	—		
C_{iss}	Input Capacitance	—	3820	—	pF	$V_{\text{GS}}=0\text{V}$
C_{oss}	Output Capacitance	—	610	—		$V_{\text{DS}}=25\text{V}$
C_{rss}	Reverse Transfer Capacitance	—	130	—		f=1.0MHz See Figure 5

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_s	Continuous Source Current (Body Diode)	—	—	75	A	MOSFET symbol showing the integral reverse p-n junction diode.
	Pulsed Source Current (Body Diode) ②	—	—	300		
V_{SD}	Diode Forward Voltage	—	—	1.3	V	$T_J=25^\circ\text{C}, I_s=40\text{A}, V_{\text{GS}}=0\text{V}$ ⑤
t_{rr}	Reverse Recovery Time	—	100	150	nS	$T_J=25^\circ\text{C}, I_F=40\text{A}$
Q_{rr}	Reverse Recovery Charge	—	410	610	nC	$dI/dt=100\text{A}/\mu\text{s}$ ⑤
t_{on}	Forward Turn-on Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_s + L_D$)				

Notes:

- ① Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 75A.
- ② Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ③ Starting $T_J = 25^\circ\text{C}$, $L = 370\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 40\text{A}$, $V_{GS}=10\text{V}$ (See Figure 12)
- ④ $I_{SD} \leq 40\text{A}$, $dI/dt \leq 300\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 175^\circ\text{C}$
- ⑤ Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.

